Vishay Siliconix

# Automotive N-Channel 40 V (D-S) 175 °C MOSFET



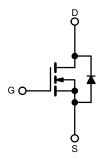
PRODUCT SUMMARY							
V <sub>DS</sub> (V)	40						
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.0080						
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.0105						
I <sub>D</sub> (A)	16						
Configuration	Single						
Package	PowerPAK 1212-8W						

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



ROHS COMPLIANT HALOGEN FREE



N-Channel MOSFET

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage	V <sub>DS</sub>	40			
Gate-source voltage		V <sub>GS</sub>	± 20	V	
Continuous dusin surrent 3	T <sub>C</sub> = 25 °C	1	16		
Continuous drain current <sup>a</sup>	T <sub>C</sub> = 125 °C	I <sub>D</sub>	16	A	
Continuous source current (diode conduction) a		I <sub>S</sub>	16		
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	64		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	25		
Single pulse avalanche energy	L = U. I MH	E <sub>AS</sub>	31.2	mJ	
Maximum navar discipation b	T <sub>C</sub> = 25 °C	D	62.5	10/	
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 125 °C	$P_{D}$	20	W	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature)	-	260	°C		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount c	$R_{thJA}$	81	°C/W
Junction-to-case (drain)		$R_{thJC}$	2.4	C/VV

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.
- e. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK 1212-8W is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		40	-	-	\ /	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{GS}$ , $I_D = 250 \mu A$	1.5	2.0	2.5	V	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 40 V	-	-	1		
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 175 °C	-	-	150		
On-state drain current a	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	20	-	-	Α	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.0065	0.0080		
Drain aguras an atata registance 3	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C	-	-	0.0113	Ω	
Drain-source on-state resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C	-	-	0.0133		
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10 A	-	0.0085	0.0105		
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		-	52	_	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	1380	1800	pF	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	850	1110		
Reverse transfer capacitance	C <sub>rss</sub>			-	40	60		
Total gate charge <sup>c</sup>	Qg		V <sub>DS</sub> = 20 V, I <sub>D</sub> = 4 A	-	22	35		
Gate-source charge c	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$		-	4	_	nC	
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	3	-		
Gate resistance	$R_g$		f = 1 MHz	0.48	0.97	1.50	Ω	
Turn-on delay time c	t <sub>d(on)</sub>			-	11	20		
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$	= 20 V, $R_L = 5 \Omega$	-	5	10		
Turn-off delay time c	t <sub>d(off)</sub>	$I_D \cong 4 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		-	25	40	ns	
Fall time <sup>c</sup>	t <sub>f</sub>			-	10	20		
Source-Drain Diode Ratings and Charact	eristic <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	64	Α	
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		-	0.82	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 5 A, dl/dt = 100 A/μs		-	44	90	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>			-	42	90	nC	
Reverse recovery fall time	ta			-	22	-		
Reverse recovery rise time	t <sub>b</sub>	1	-	25	-	ns		
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>		-	-1.8	-4	Α		

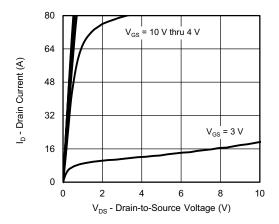
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

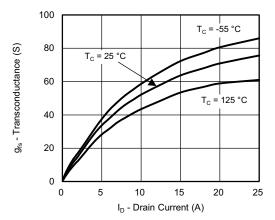
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



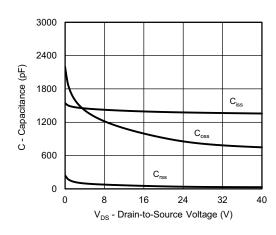
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



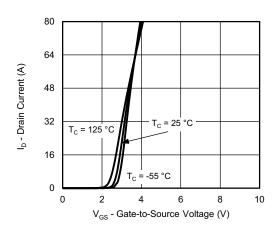
#### **Output Characteristics**



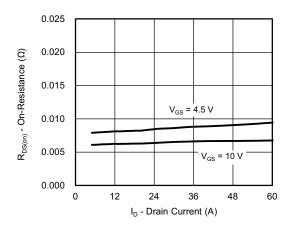
#### Transconductance



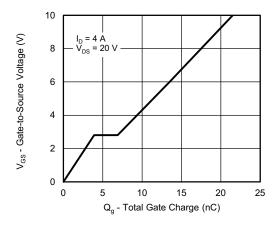
Capacitance



#### **Transfer Characteristics**



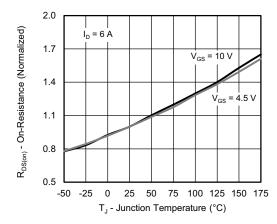
#### On-Resistance vs. Drain Current



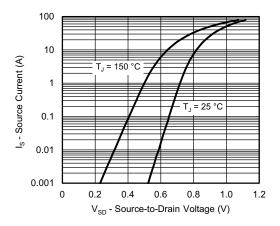
Gate Charge



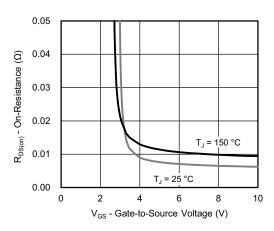
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



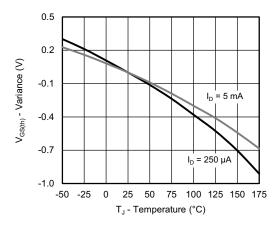
On-Resistance vs. Junction Temperature



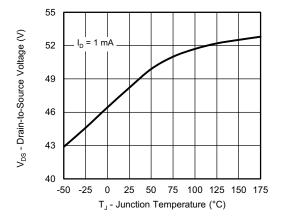
**Source Drain Diode Forward Voltage** 



On-Resistance vs. Gate-to-Source Voltage



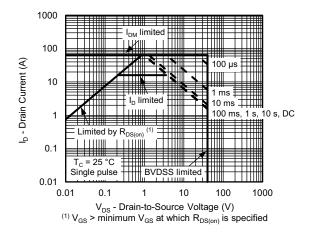
Threshold Voltage



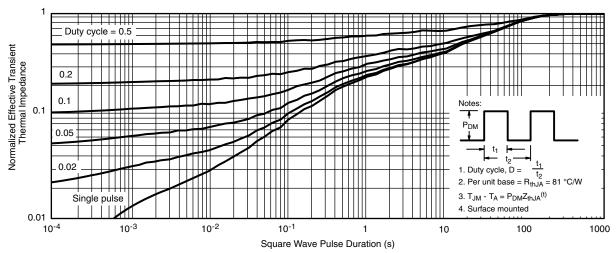
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



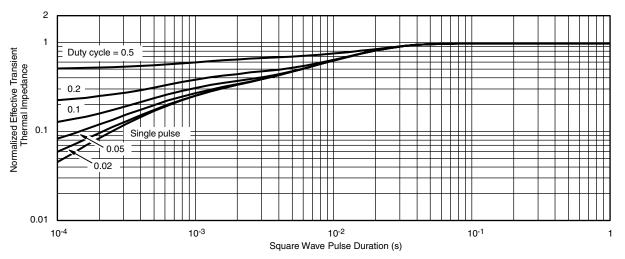
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

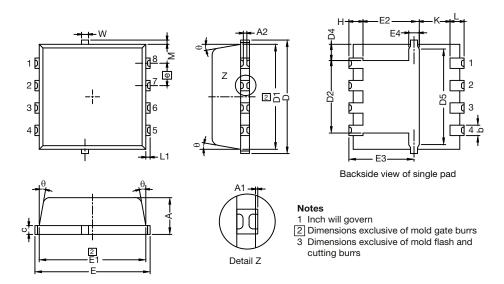
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?62896">www.vishay.com/ppg?62896</a>.



# PowerPAK® 1212-8W Case Outline



DIM.		MILLIMETERS		INCHES				
DIM.	MIN.	MIN. NOM.		MIN. NOM. MAX.		MIN.	NOM.	MAX.
Α	0.97	1.04	1.12	0.038	0.041	0.044		
A1	0	-	0.05	0	-	0.002		
A2	0	-	0.13	0	-	0.005		
b	0.23	0.30	0.41	0.009	0.012	0.016		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	3.20	3.30	3.40	0.126	0.130	0.134		
D1	2.95	3.05	3.15	0.116	0.120	0.124		
D2	1.98	2.11	2.24	0.078	0.083	0.088		
D4		0.47 typ.		0.0185 typ.				
D5		2.3 typ.		0.090 typ.				
Е	3.20	3.30	3.40	0.126	0.130	0.134		
E1	2.95	3.05	3.15	0.116	0.120	0.124		
E2	1.47	1.60	1.73	0.058	0.063	0.068		
E3	1.75	1.85	1.98	0.069	0.073	0.078		
E4		0.34 typ.		0.013 typ.				
е		0.65 BSC.			0.026 BSC			
K		0.86 typ.			0.034 typ.			
Н	0.30	0.41	0.51	0.012	0.016	0.020		
L	0.30	0.43	0.56	0.012	0.017	0.022		
L1	0.06	0.13	0.20	0.002	0.005	0.008		
θ	0°	-	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.014		
М		0.125 typ.			0.005 typ.			

DWG: 6032



# PowerPAK® 1212 Mounting and Thermal Considerations

#### Johnson Zhao

MOSFETs for switching applications are now available with die on resistances around 1 m $\Omega$  and with the capability to handle 85 A. While these die capabilities represent a major advance over what was available just a few years ago, it is important for power MOSFET packaging technology to keep pace. It should be obvious that degradation of a high performance die by the package is undesirable. PowerPAK is a new package technology that addresses these issues. The PowerPAK 1212-8 provides ultra-low thermal impedance in a small package that is ideal for space-constrained applications. In this application note, the PowerPAK 1212-8's construction is described. Following this, mounting information is presented. Finally, thermal and electrical performance is discussed.

#### THE PowerPAK PACKAGE

The PowerPAK 1212-8 package (Figure 1) is a derivative of PowerPAK SO-8. It utilizes the same packaging technology, maximizing the die area. The bottom of the die attach pad is exposed to provide a direct, low resistance thermal path to the substrate the device is mounted on. The PowerPAK 1212-8 thus translates the benefits of the PowerPAK SO-8 into a smaller package, with the same level of thermal performance. (Please refer to application note "PowerPAK SO-8 Mounting and Thermal Considerations.")



Figure 1. PowerPAK 1212 Devices

The PowerPAK 1212-8 has a footprint area comparable to TSOP-6. It is over 40 % smaller than standard TSSOP-8. Its die capacity is more than twice the size of the standard TSOP-6's. It has thermal performance an order of magnitude better than the SO-8, and 20 times better than TSSOP-8. Its thermal performance is better than all current SMT packages in the market. It will take the advantage of any PC board heat sink capability. Bringing the junction temperature down also increases the die efficiency by around 20 % compared with TSSOP-8. For applications where bigger packages are typically required solely for thermal consideration, the PowerPAK 1212-8 is a good option.

Both the single and dual PowerPAK 1212-8 utilize the same pin-outs as the single and dual PowerPAK SO-8. The low 1.05 mm PowerPAK height profile makes both versions an excellent choice for applications with space constraints.

#### **PowerPAK 1212 SINGLE MOUNTING**

To take the advantage of the single PowerPAK 1212-8's thermal performance see Application Note 826,

Recommended Minimum Pad Patterns With Outline Drawing Access for Vishay Siliconix MOSFETs. Click on the PowerPAK 1212-8 single in the index of this document.

In this figure, the drain land pattern is given to make full contact to the drain pad on the PowerPAK package.

This land pattern can be extended to the left, right, and top of the drawn pattern. This extension will serve to increase the heat dissipation by decreasing the thermal resistance from the foot of the PowerPAK to the PC board and therefore to the ambient. Note that increasing the drain land area beyond a certain point will yield little decrease in foot-to-board and foot-to-ambient thermal resistance. Under specific conditions of board configuration, copper weight, and layer stack, experiments have found that adding copper beyond an area of about 0.3 to 0.5 in<sup>2</sup> of will yield little improvement in thermal performance.

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#### PowerPAK 1212 DUAL

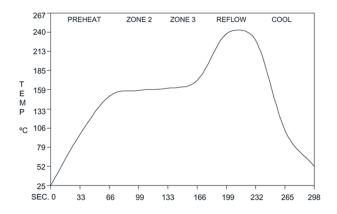
To take the advantage of the dual PowerPAK 1212-8's thermal performance, the minimum recommended land pattern can be found in Application Note 826, Recommended Minimum Pad Patterns With Outline Drawing Access for Vishay Siliconix MOSFETs. Click on the PowerPAK 1212-8 dual in the index of this document.

The gap between the two drain pads is 10 mils. This matches the spacing of the two drain pads on the PowerPAK 1212-8 dual package.

This land pattern can be extended to the left, right, and top of the drawn pattern. This extension will serve to increase the heat dissipation by decreasing the thermal resistance from the foot of the PowerPAK to the PC board and therefore to the ambient. Note that increasing the drain land area beyond a certain point will yield little decrease in foot-to-board and foot-toambient thermal resistance. Under specific conditions of board configuration, copper weight, and layer stack, experiments have found that adding copper beyond an area of about 0.3 to 0.5 in<sup>2</sup> of will yield little improvement in thermal performance.

#### **REFLOW SOLDERING**

Vishay Siliconix surface-mount packages meet solder reflow reliability requirements. Devices are subjected to solder reflow as a preconditioning test and are then reliability-tested using temperature cycle, bias humidity, HAST, or pressure pot. The solder reflow temperature profile used, and the temperatures and time duration, are shown in Figures 2 and 3. For the lead (Pb)-free solder profile, see http://www.vishay.com/ doc?73257.



Ramp-Up Rate	+ 6 °C /Second Maximum
Temperature at 155 ± 15 °C	120 Seconds Maximum
Temperature Above 180 °C	70 - 180 Seconds
Maximum Temperature	240 + 5/- 0 °C
Time at Maximum Temperature	20 - 40 Seconds
Ramp-Down Rate	+ 6 °C/Second Maximum

Figure 2. Solder Reflow Temperature Profile

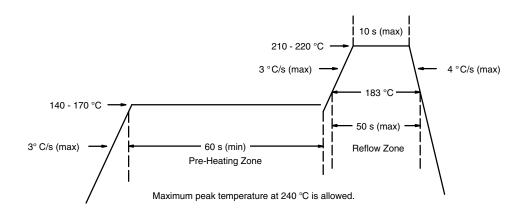


Figure 3. Solder Reflow Temperatures and Time Durations

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TABLE 1: EQIVALENT STEADY STATE PERFORMANCE										
Package	sc	SO-8 TSOP-8 TSOP-8 PPAK 1212 PPAK					SO-8			
Configuration	Single	Dual	Single	Dual	Single	Dual	Single	Dual	Single	Dual
Thermal Resiatance R <sub>thJC</sub> (C/W)	20	40	52	83	40	90	2.4	5.5	1.8	5.5

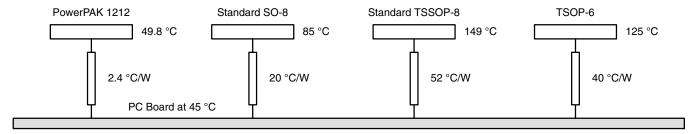


Figure 4. Temperature of Devices on a PC Board

#### THERMAL PERFORMANCE

#### Introduction

A basic measure of a device's thermal performance is the junction-to-case thermal resistance,  $R\theta jc$ , or the junction to- foot thermal resistance,  $R\theta jf$ . This parameter is measured for the device mounted to an infinite heat sink and is therefore a characterization of the device only, in other words, independent of the properties of the object to which the device is mounted. Table 1 shows a comparison of the PowerPAK 1212-8, PowerPAK SO-8, standard TSSOP-8 and SO-8 equivalent steady state performance.

By minimizing the junction-to-foot thermal resistance, the MOSFET die temperature is very close to the temperature of the PC board. Consider four devices mounted on a PC board with a board temperature of 45 °C (Figure 4). Suppose each device is dissipating 2 W. Using the junction-to-foot thermal resistance characteristics of the PowerPAK 1212-8 and the other SMT packages, die temperatures are determined to be 49.8 °C for the PowerPAK 1212-8, 85 °C for the standard SO-8, 149 °C for standard TSSOP-8, and 125 °C for TSOP-6. This is a 4.8 °C rise above the board temperature for the PowerPAK 1212-8, and over 40 °C for other SMT packages. A 4.8 °C rise has minimal effect on  $r_{\rm DS(ON)}$  whereas a rise of over 40 °C will cause an increase in  $r_{\rm DS(ON)}$  as high as 20 %.

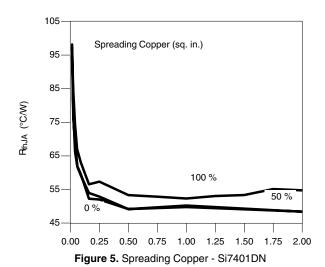
#### **Spreading Copper**

Designers add additional copper, spreading copper, to the drain pad to aid in conducting heat from a device. It is helpful to have some information about the thermal performance for a given area of spreading copper.

Figure 5 and Figure 6 show the thermal resistance of a PowerPAK 1212-8 single and dual devices mounted on a 2-in. x 2-in., four-layer FR-4 PC boards. The two internal layers and the backside layer are solid copper. The internal layers were chosen as solid copper to model the large power and ground planes common in many applications. The top layer was cut back to a smaller area and at each step junction-to-ambient thermal resistance measurements were taken. The results indicate that an area above 0.2 to 0.3 square inches of spreading copper gives no additional thermal performance improvement. A subsequent experiment was run where the copper on the back-side was reduced, first to 50 % in stripes to mimic circuit traces, and then totally removed. No significant effect was observed.

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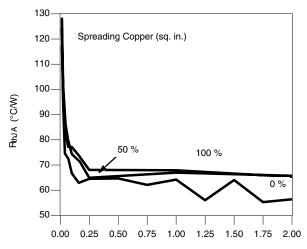


Figure 6. Spreading Copper - Junction-to-Ambient Performance

### **CONCLUSIONS**

As a derivative of the PowerPAK SO-8, the PowerPAK 1212-8 uses the same packaging technology and has been shown to have the same level of thermal performance while having a footprint that is more than 40 % smaller than the standard TSSOP-8.

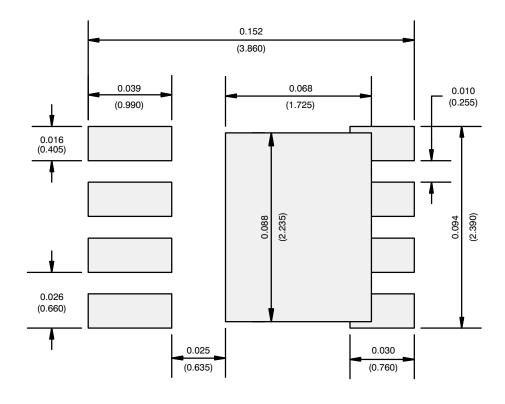
Recommended PowerPAK 1212-8 land patterns are provided to aid in PC board layout for designs using this new package.

The PowerPAK 1212-8 combines small size with attractive thermal characteristics. By minimizing the thermal rise above the board temperature, PowerPAK simplifies thermal design considerations, allows the device to run cooler, keeps r<sub>DS(ON)</sub> low, and permits the device to handle more current than a same- or larger-size MOS-FET die in the standard TSSOP-8 or SO-8 packages.

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## RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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многоканальный

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Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

### http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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